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(54) SEMICONDUCTOR DEVICE AND MANUFACTURE THEREOF

(57) Abstract:

PURPOSE: To enable to perform a functional inspection on the level of a semiconductor element and to facilitate a higher density-mounting on a wiring substrate by a method wherein the semiconductor element is connected to an electrode terminal adhered to the main surface of a frame body at one end thereof which has protruded to the inner direction of the electrode terminal, the other end is cut at a prescribed place and the bent part of the connected element is adhered to the side of the frame body.

CONSTITUTION: An electrode terminal 23 has been adhered on an insulative resin 22. The protruded electrode 25 of a semiconductor element 21 is joined to one side of the electrode terminal 23 and after a coating was performed with a resin 26, the connected semiconductor element 21 is cut at A and A'. In this condition, the electrode terminal 23 is bent along the side of the frame body 22 and adhered. In this case, a connecting with external circuits is performed at the bent part 24 of the electrode terminal 23. The electrode terminal 24 has been made into a nearly equal length to the thickness of the frame body 22, but it is better to shorten according to circumstances.

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